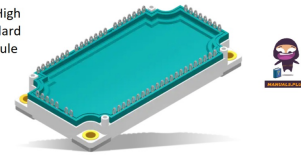


IXYS MDNA3High
Voltage Standard
Rectifier Module



IXYS MDNA3High Voltage Standard Rectifier Module Owner's Manual

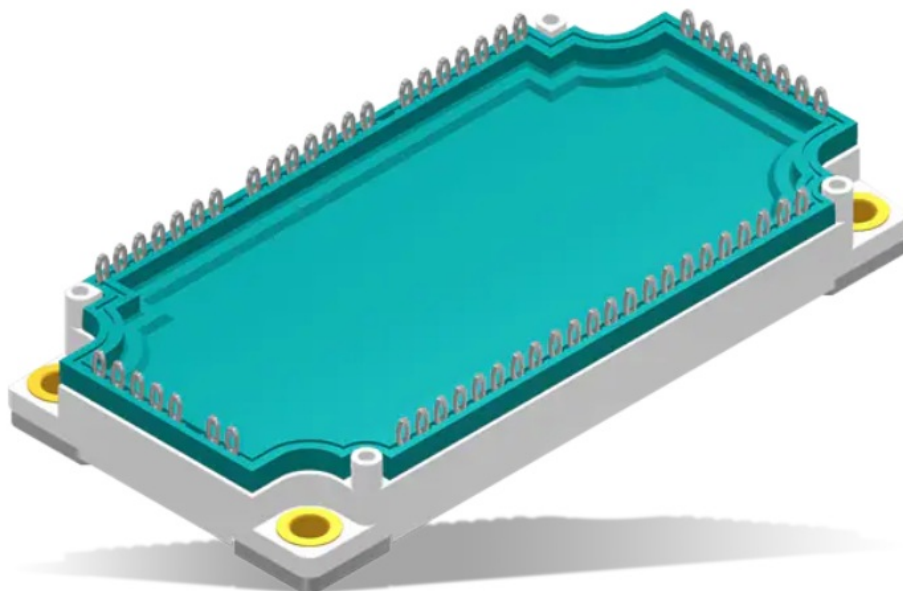
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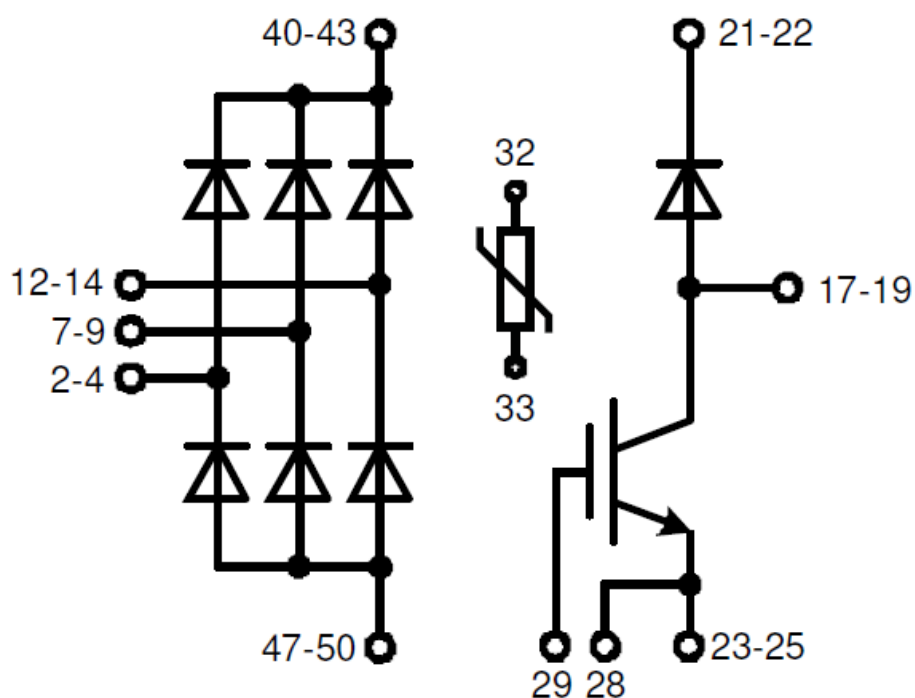


IXYS MDNA3High Voltage Standard Rectifier Module



Part number

MDNA360UB2200PTED



3~ Rectifier	Brake Chopper
VRRM = 2200 V	VCES = 1700 V
IDAV = 360 A	IC25 = 200 A
IFSM = 1900 A	VCE(sat) = 2,1 V

Features / Advantages:

Brake with Infineon IGBT³

Applications

3~ Rectifier with brake unit for drive inverters

Package: E2-Pack

- Isolation Voltage: 4 3 0 0 V~
- Industry standard outline
- RoHS compliant
- PressFit-Pins for PCB mounting
- Height: 17 mm
- Base plate: Copper internally DCB isolated
- Advanced power cycling
- Phase Change Material available

Disclaimer Notice

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Rectifier				Ratings			
Sym bol	Definition	Conditions		mi n.	ty p.	ma x.	U ni t
VRS M	<i>max. non-repetitive reverse blocking voltage</i>	$T_{VJ} = 25^{\circ}\text{C}$				23 00	V
VRR M	<i>max. repetitive reverse blocking voltage</i>	$T_{VJ} = 25^{\circ}\text{C}$				22 00	V
I_R	<i>reverse current</i>	$V_R = 2200\text{ V}$	$T_{VJ} = 25^{\circ}\text{C}$			10 0	μ A
	$V_R = 2200\text{ V}$		$T_{VJ} = 150^{\circ}\text{C}$			3	m A
VF	<i>forward vo ltage drop</i>	$I_F = 120\text{ A}$ $= 25^{\circ}\text{C}$	T_{VJ}			1,2 5	V
		$I_F = 360\text{ A}$				1,8 0	V
		$I_F = 120\text{ A}$ $= 125^{\circ}\text{C}$	T_{VJ}			1,2 3	V
		$I_F = 360\text{ A}$				1,9 8	V
I DA V	<i>bridge output current</i> <i>rectangular</i>	$T_C = 85^{\circ}\text{C}$ $d = \frac{1}{3}$	$TVJ = 150^{\circ}\text{C}$			36 0	A
VF0 r_F	<i>threshold voltage</i> <i>for power loss calculation only</i> <i>slope resistance</i>		$TVJ = 150^{\circ}\text{C}$			0,8 2	V
						3,4	m Ω

RthJC	<i>thermal resistance junction to case</i>					0,25	K/W
RthCH	<i>thermal resistance case to heatsink</i>				0,1		K/W
Ptot	<i>total power dissipation</i>			$T_C = 25^{\circ}\text{C}$		500	W
IFSM <i>max. forward surge current</i>	$t = 10 \text{ ms; (50 Hz), sine}$ $T_{VJ} = 45^{\circ}\text{C}$					1,90	kA
	$t = 8,3 \text{ ms; (60 Hz), sine}$ $V_R = 0 \text{ V}$					2,05	kA
	$t = 10 \text{ ms; (50 Hz), sine}$ $T_{VJ} = 150^{\circ}\text{C}$					1,62	kA
	$t = 8,3 \text{ ms; (60 Hz), sine}$ $V_R = 0 \text{ V}$					1,75	kA
I²t <i>value for fusing</i>	$t = 10 \text{ ms; (50 Hz), sine}$ $T_{VJ} = 45^{\circ}\text{C}$					18,1	kA ² s
	$t = 8,3 \text{ ms; (60 Hz), sine}$ $V_R = 0 \text{ V}$					17,5	kA ² s
	$t = 10 \text{ ms; (50 Hz), sine}$ $T_{VJ} = 150^{\circ}\text{C}$					13,0	kA ² s
	$t = 8,3 \text{ ms; (60 Hz), sine}$ $V_R = 0 \text{ V}$					12,7	kA ² s
C_J	<i>junction capacitance</i> $V_R = 400 \text{ V; } f = 1 \text{ MHz}$			$T_{VJ} = 25^{\circ}\text{C}$		73	pF

Brake IGBT + Diode					Ratings			
Symbol	Definition	Conditions			min.	typ.	max.	Unit
VCES	<i>collector emitter voltage</i>		T_{VJ}	$= 25^{\circ}\text{C}$			1700	V
VGES	<i>max. DC gate voltage</i>						±20	V
VGEM	<i>max. transient gate emitter voltage</i>						±30	V
IC25	<i>collector current</i>		T_C	$= 25^{\circ}\text{C}$			200	A
IC100			T_C	$= 100^{\circ}\text{C}$			135	A
Ptot	<i>total power dissipation</i>		T_C	$= 25^{\circ}\text{C}$			935	W

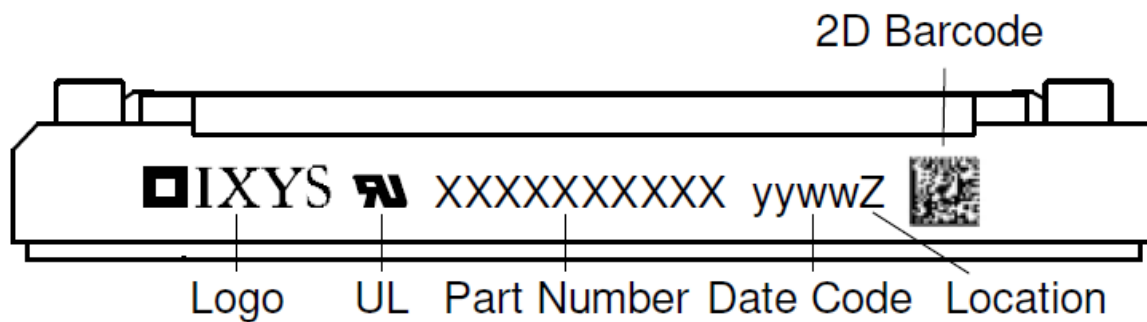
VCE(sat)	collector emitter saturation voltage	IC = 150 A; VGE = 15 V	T VJ	= 25°C		2,1	2,8	V
			T VJ	= 125°C		3,2		V
VGE(th)	gate emitter threshold voltage	IC = 4 mA; VGE = VCE	T VJ	= 25°C	5,5	6,0	6,5	V
ICES	collector emitter leakage current	VCE = VCES; VGE = 0 V	T VJ T VJ	= 25°C = 125°C		2,3	0,12	mA mA
IGES	gate emitter leakage current	VGE = ±20 V					500	nA
QG(on)	total gate charge	VCE = 900 V; VGE = 15 V; IC = 150 A				310		nC
td(on)	turn-on delay time	inductive load VCE = 900 V; IC = 150 A VGE = ±15 V; RG = 10 Ω	T VJ	= 125°C		120		ns
tr	time turn-off delay time					80		ns
td(off)	time turn-off delay time					400		ns
t f	turn-on energy per pulse					150		ns
Eon	turn-on energy per pulse					45		mJ
Eoff	turn-off energy per pulse					50		mJ
RBSOA ICM	reverse bias safe operating area	VGE = ±15 V; RG = 10 Ω VCEK = 1700 V	T VJ	= 125°C			280	A
SCSOA	short circuit safe operating area	VCEK = 1700 V						
tSC	short circuit duration	VCE = 1300 V; VGE = ±15	T VJ	= 125°C			10	μs
ISC	short circuit current	RG = 10 Ω; non-repetitive				400		A
RthJC	thermal resistance junction to case						0,16	K/W
RthCH	thermal resistance case to heatsink					0,25		K/W
							1700	V
Brake Diode								
VRRM	max. repetitive reverse voltage		T VJ	= 25°C				

IF25	<i>forward current</i>		T_C	= 25°C			145	A
IF100			T_C	= 100°C			90	A
V_F	<i>forward voltage</i>	$I_F = 100\text{ A}$	T_{VJ}	= 25°C				V
			T_{VJ}	= 125°C		2,00	2,20	V
IR	<i>reverse current</i>	$V_R = V_{RRM}$	T_{VJ}	= 25°C			tbd	mA
			T_{VJ}	= 125°C			tbd	mA
Qrr	<i>reverse recovery charge</i>	$V_R = 900\text{ V}$				30		μC
IRM	<i>max. reverse recovery current</i>	$-di_F/dt = 2500\text{ A}/\mu\text{s}$	T_{VJ}	= 125°C		60		A
trr	<i>reverse recovery time</i>	$I_F = 100\text{ A}; V_{GE} = 0\text{ V}$				200		ns
Erec	<i>reverse recovery energy</i>					11		mJ
RthJC	<i>thermal resistance junction to case</i>						0,39	K/W
RthCH	<i>thermal resistance case to heatsink</i>					0,62		K/W

Package E2-Pack			Ratings			
Symbol	Definition	Conditions	min .	typ.	max .	Unit
I_{RMS}	<i>RMS current</i>	per terminal			30	A
T_{VJ}	<i>virtual junction temperature</i>		-40		150	°C
Top	<i>operation temperature</i>		-40		125	°C
T_{stg}	<i>storage temperature</i>		-40		125	°C
Weight				176		g
MD	<i>mounting torque</i>		3		6	N m
dSpp/App	<i>terminal to terminal</i> <i>creepage distance on surface / striking distance through air</i>		6,0			m m
dSpb/Apb		<i>terminal to backside</i>	12, 0			m m
V	<i>isolation voltage</i>	t = 1 second	430 0			V
ISOL		50/60 Hz, RMS;				V
IISOL ≤ 1 mA			360 0			V
t = 1 minute						

Part description

M = Module
 D = Diode
 N = High Voltage Standard Rectifier
 A = (>= 2000V)
 360 = Current Rating [A]
 UB = 3~ Rectifier Bridge + Brake Unit
 2200 = Reverse Voltage [V]
 PT = PressFit-Pin, Thermistor
 ED = E2-Pack
 - = Hyphen
 PC = Phase Change Material



Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MDNA360UB2200PTED	MDNA360UB2200PTED	Blister	28	515682
Alternative	MDNA360UB2200PTED-PC	MDNA360UB2200PTED	Blister	28	514541

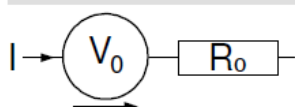
Temperature Sensor NTC

Symbol	Definition	Conditions	min.	typ.	max.	Unit
R25 B25/50	<i>resistance</i>	$T_{VJ} = 25^{\circ}$	4,85	5	5,15	k Ω
	<i>temperature coefficient</i>			3375		K

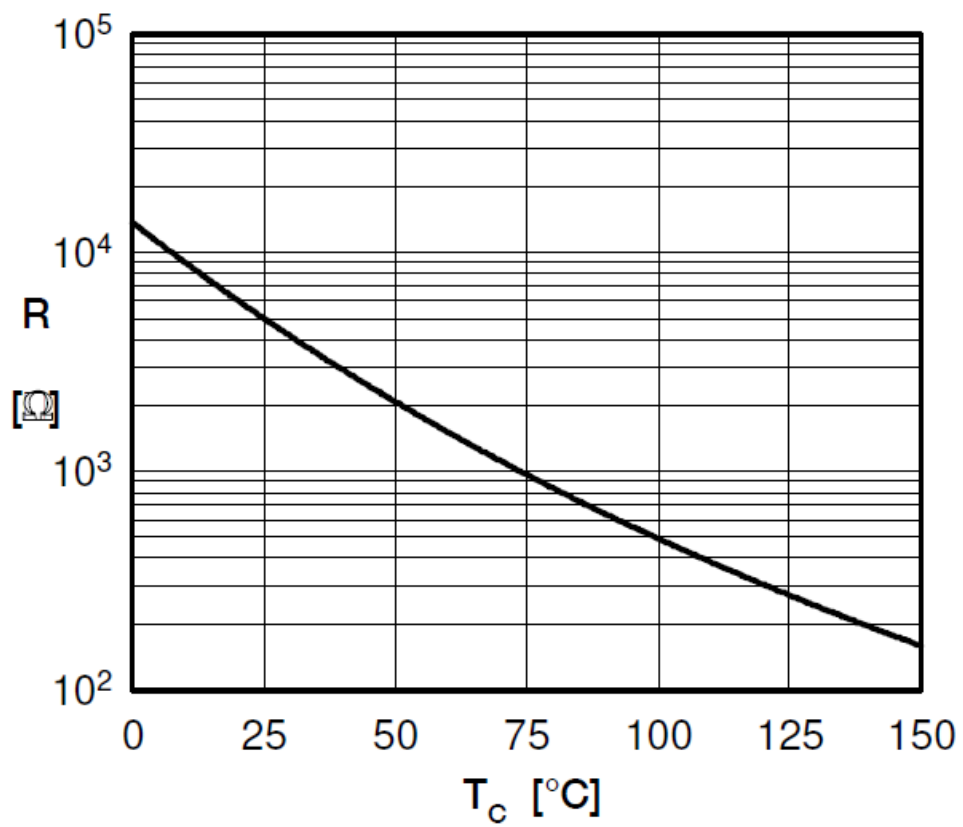
Equivalent Circuits for Simulation

* on die level

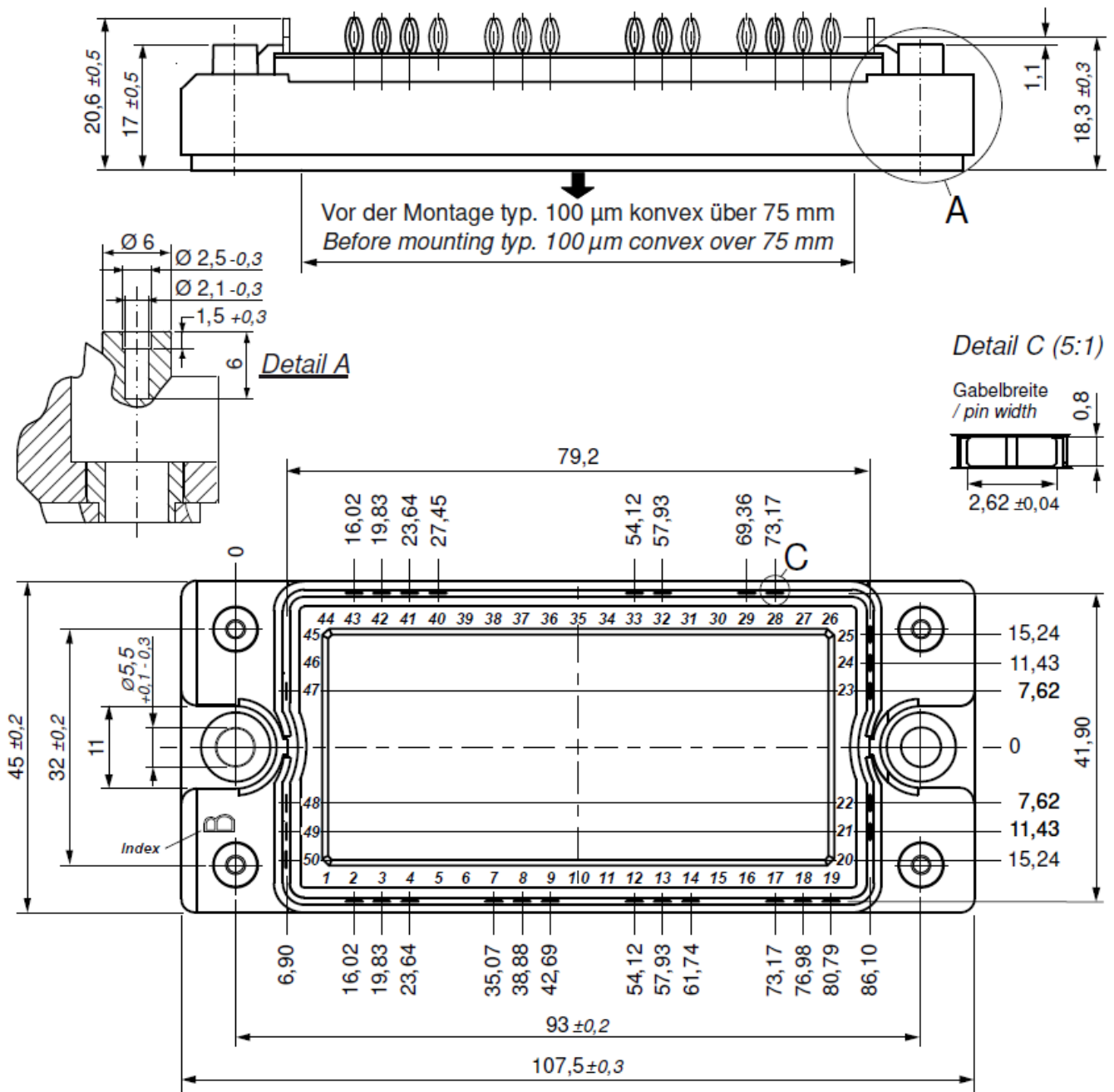
$T_{VJ} = 150^{\circ}\text{C}$



		Rectifier	Brake IGBT +	Brake Diode	
$V_{0\text{ max}}$	<i>threshold voltage</i>	0,82	1,1	1,25	V
$R_{0\text{ max}}$	<i>slope resistance *</i>	1,5	9,2	8,5	m Ω



Typ. NTC resistance vs. temperature



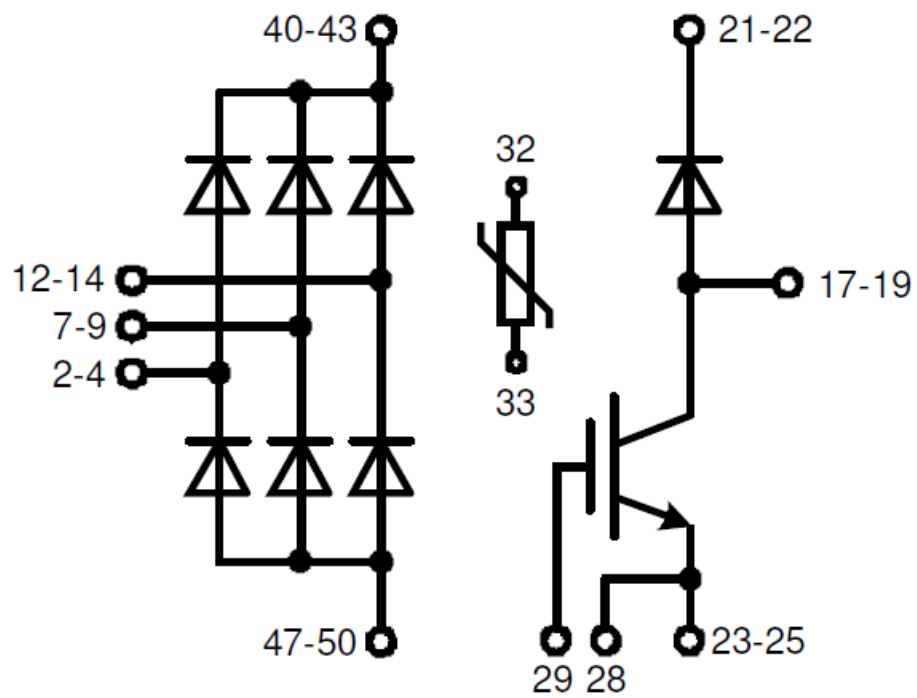
Bemerkung / Note:

- Measure without tolerances according DIN ISO 2768-T1-m
- PCB hole pattern: see pin position
- Tolerance of pin position and PCB hole pattern: 0.1
- Diameter of drill: $\varnothing 2.35 \text{ mm}$
- Diameter of plated holes: $\varnothing 2.14 - 2.29 \text{ mm}$ (Cu thickness in via typ. $50 \mu\text{m}$)
- Plating: chem. Sn max. $15 \mu\text{m}$
- Insert Force: per terminal with a typ. insert speed of 7 mm/s : typ. 90 N
- Further information: www.ixys.com Application note IXAN0077
- Mounting instruction: www.ixys.com Application note IXAN0024

Detail A: Mounting on PCB

- Recommended, self-tapping screw: EJOT PT® (size: K25)

- Max. screw length: PCB-Dicke / thickness + 6 mm (hole depth)
- Recommended mounting torque: 1.5 Nm



Rectifier

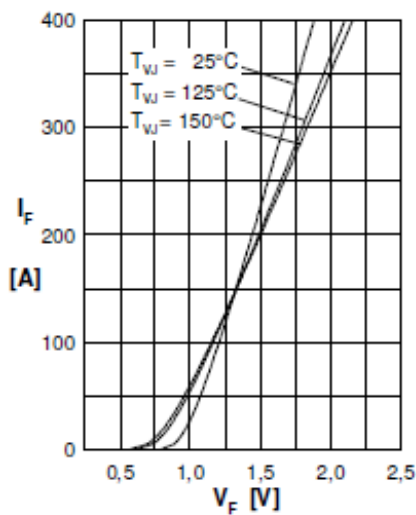


Fig. 1 Forward current versus voltage drop per diode

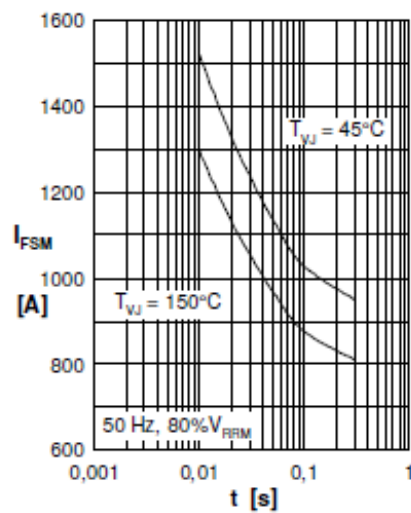


Fig. 2 Surge overload current vs. time per diode

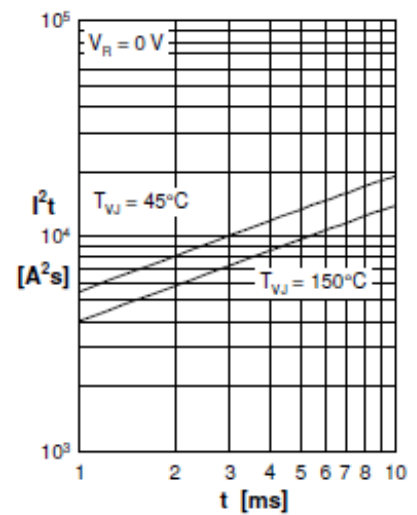


Fig. 3 I^2t versus time per diode

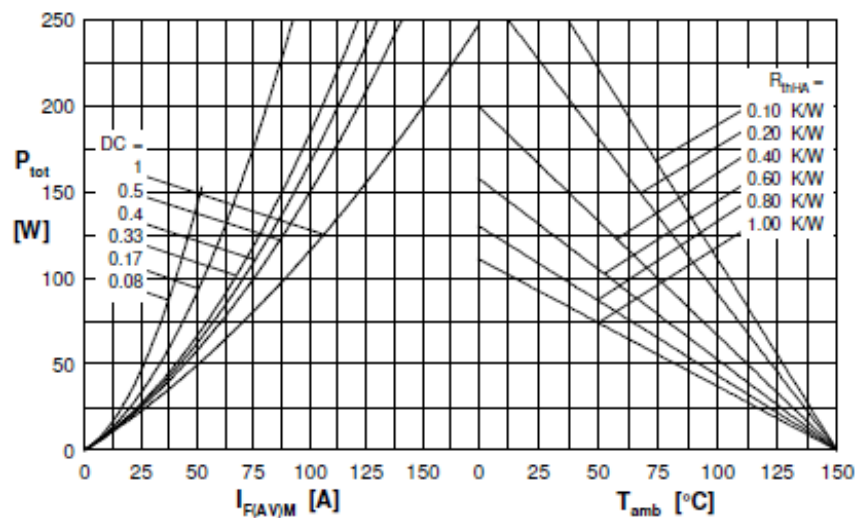


Fig. 4 Power dissipation vs. forward current and ambient temperature per diode

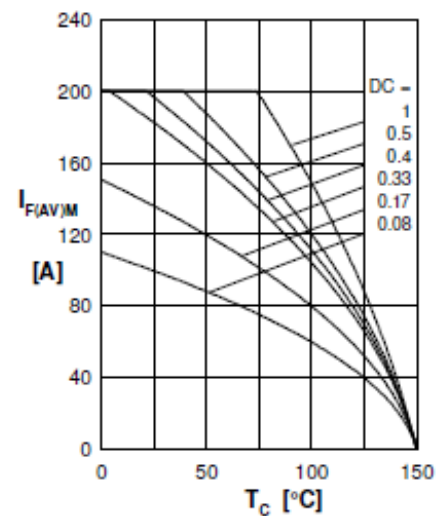


Fig. 5 Max. forward current vs. case temperature per diode

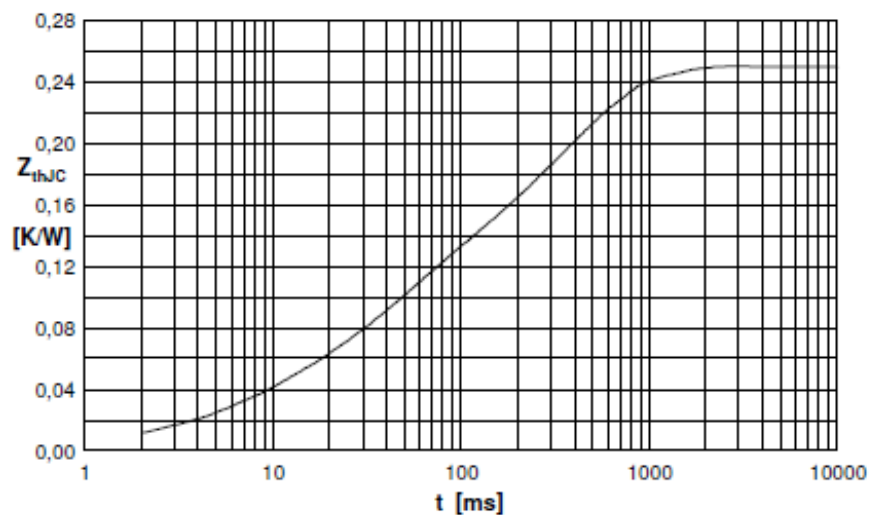


Fig. 6 Transient thermal impedance junction to case vs. time per diode

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.020	0.006
2	0.003	0.007
3	0.080	0.037
4	0.147	0.360

Brake IGBT + Diode

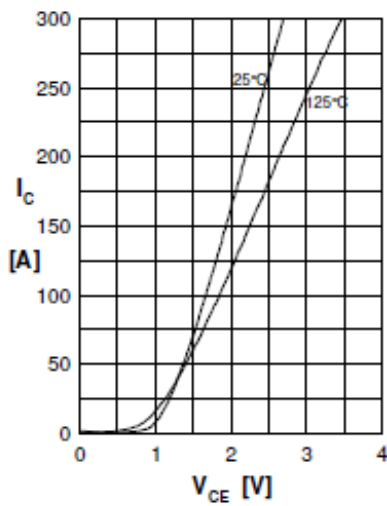


Fig.1 Typ. output characteristics IGBT

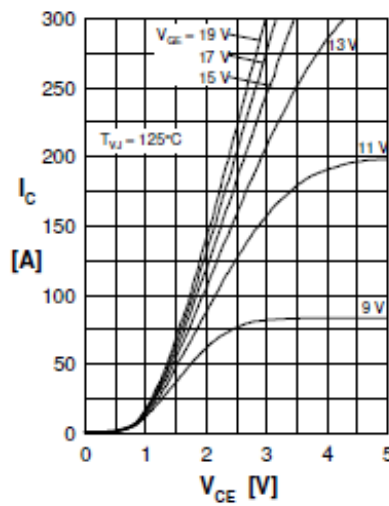


Fig.2 Typ. output characteristics IGBT

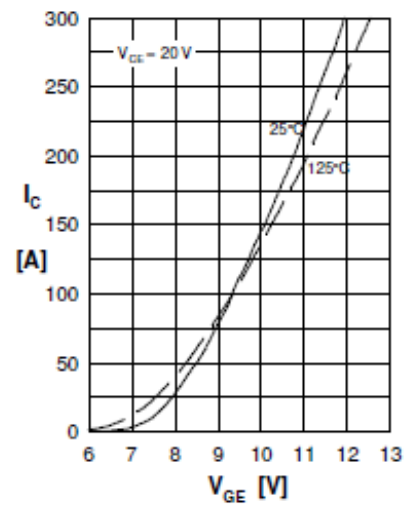


Fig.3 Typ. transfer charact. IGBT

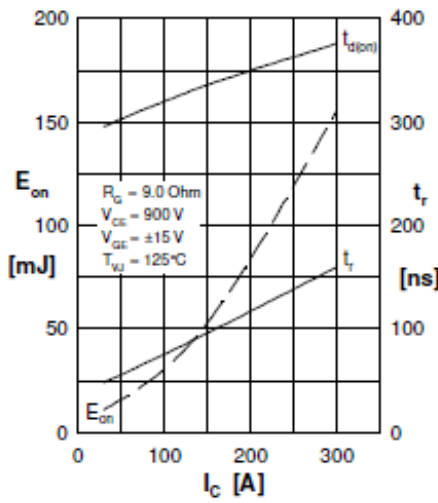


Fig.4 Typ. turn-on energy & switch. times vs. collector current

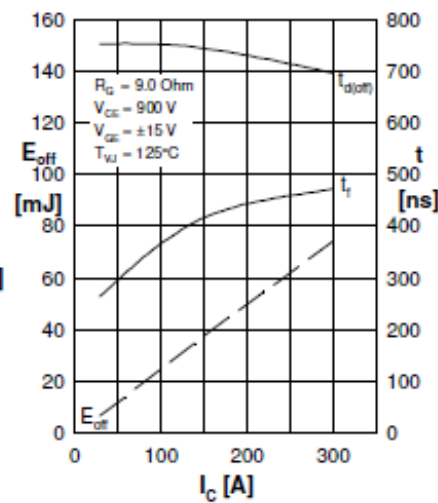


Fig.5 Typ. turn-off energy & switch. times vs. collector current

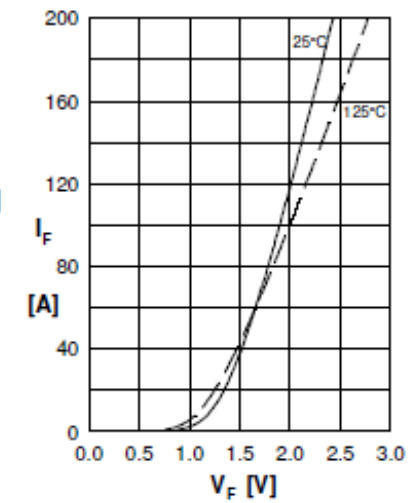


Fig.6 Typ. forward characteristics Diode

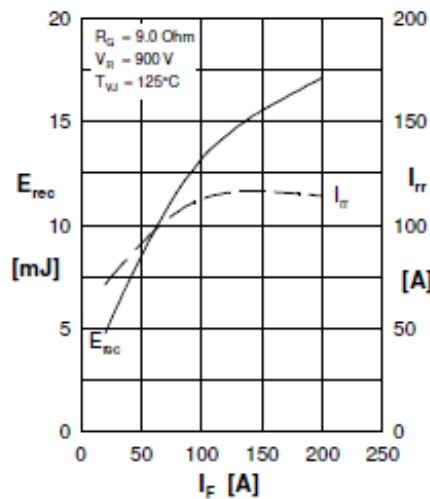


Fig.7 Typ. reverse recovery characteristics Diode

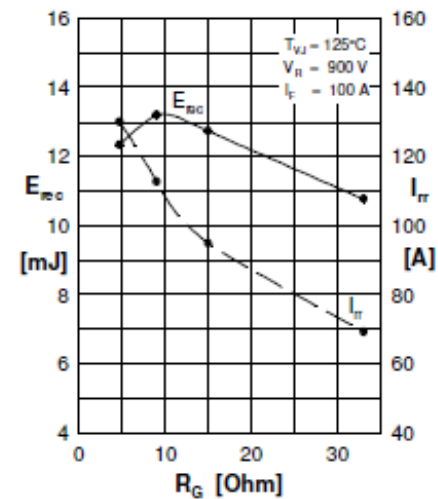


Fig.8 Typ. reverse recovery characteristics Diode

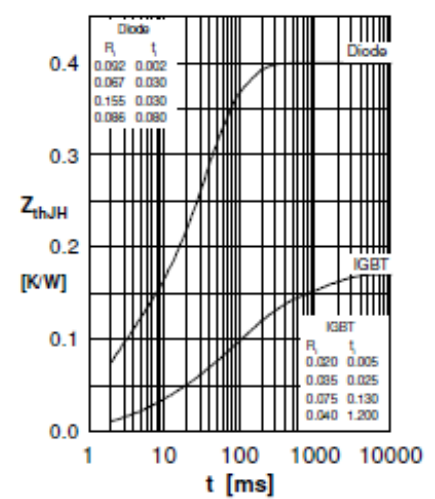
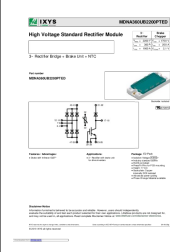


Fig.9 Typ. transient thermal resistance junction to heatsink



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High Voltage Standard Rectifier Module
MDNA360UB2200PTED, MDNA3 High Voltage Standard Rectifier Module, MDNA3, High Voltage Standard Rectifier Module, Voltage Standard Rectifier Module, Standard Rectifier Module, Rectifier Module

References

- [!\[\]\(998e30a8dcfb35e9b724d9eb41990449_img.jpg\) IXYS](#)
- [!\[\]\(8c6ce7139abaf965e82cfcdd29561d57_img.jpg\) Product Disclaimer - Littelfuse](#)
- [User Manual](#)

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